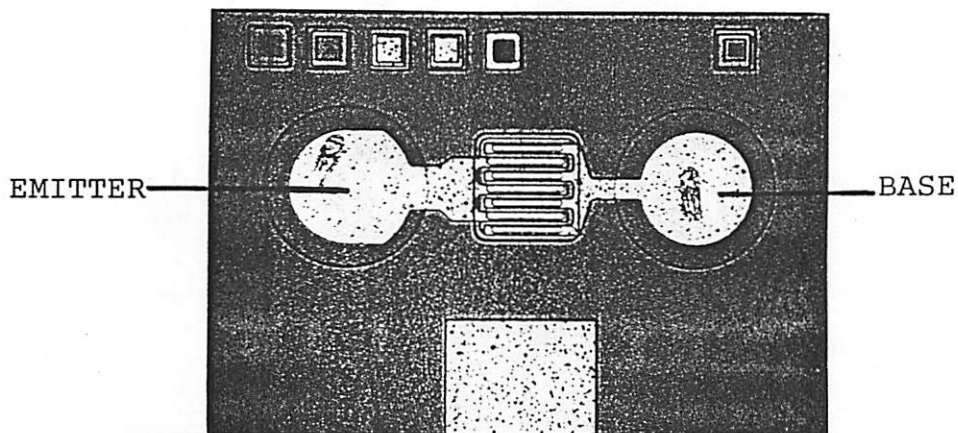


DIE TECHNOLOGY LIMITED



CHIP BACK IS COLLECTOR

E & O E. The supply of dice to this layout can only be guaranteed if it forms part of a specification or the chip identification, where given below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection, or it is the potential to which the chip back must be connected when specifically stated in a NOTE above. If no potential is given the chip back should be isolated. Nominal metallisation thicknesses are based on manufacturer's information. 1 mil. = 0.001 inch. Tolerances on dimensions +/- 3 mils.

<p><u>Approved:</u> <i>[Signature]</i> <u>Date:</u> 27-10-95</p>	<p><u>Metallisation/Thickness (KA)</u> Top : Al 12 Back: Au 15</p> <p>Back Potential: Collector Man's. Part No:</p>	<p><u>Chip Identification</u> Line Source: Mask Ref : Process : Version : Geometry : G48</p>
<p>Corbrook Road Chadderton Lancs. OL9 9SD</p> <p>Tel: 0161 626 3827 Fax: 0161 627 2341</p>	<p><u>Chip Dimensions (mils.):</u> 20 x 15 x 5</p>	<p><u>Bond Pads:</u> 2 ϕ</p>
<p>ZETEX BFY90</p>		<p>Issue 2</p>